



Material Content Data Sheet



Sales Product Name		BSO301SP H		Issued		27. September 2017		
MA#		MA000734724						
Package		PG-DSO-8-39		Weight*		84.24 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.914	4.65	4.65	46468	46468
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		122	
	non noble metal	zinc	7440-66-6	0.041	0.05		486	
	non noble metal	iron	7439-89-6	0.820	0.97		9728	
wire	non noble metal	copper	7440-50-8	33.276	39.50	40.53	395015	405351
	non noble metal	copper	7440-50-8	0.236	0.28	0.28	2806	2806
	encapsulation	organic material	carbon black	1333-86-4	0.220	0.26		2613
encapsulation	plastics	epoxy resin	-	6.825	8.10		81015	
	inorganic material	silicondioxide	60676-86-0	36.985	43.91	52.27	439047	522675
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9661	9661
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	862	862
glue	plastics	epoxy resin	-	0.154	0.18		1827	
	noble metal	silver	7440-22-4	0.872	1.03	1.21	10350	12177
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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